

**Rochester Electronics
Manufactured Components**

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

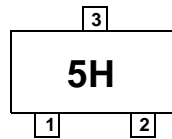
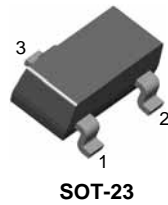
- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

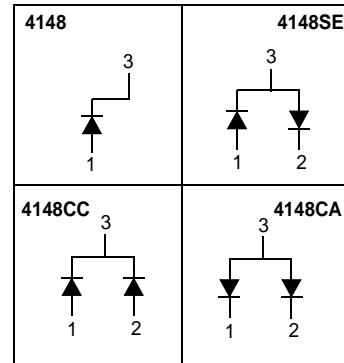
MMBD4148/SE/CC/CA

MMBD4148/SE/CC/CA



MARKING
MMBD4148 5H MMBD4148CA D6
MMBD4148CC D5 MMBD4148SE D4

Connection Diagram



Small Signal Diode

Absolute Maximum Ratings * $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Maximum Repetitive Reverse Voltage	100	V
$I_{F(AV)}$	Average Rectified Forward Current	200	mA
I_{FSM}	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second Pulse Width = 1.0 microsecond	1.0	A
		2.0	A
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_J	Operating Junction Temperature	150	$^\circ\text{C}$

* These ratings are limiting values above which the serviceability of the diode may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
P_D	Power Dissipation	350	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	$^\circ\text{C/W}$

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_R	Breakdown Voltage	$I_R = 5.0\mu\text{A}$	75		V
		$I_R = 100\mu\text{A}$	100		V
V_F	Forward Voltage	$I_F = 10\text{mA}$		1.0	V
I_R	Reverse Leakage Current	$V_R = 20\text{V}$		25	nA
		$V_R = 20\text{V}, T_A = 150^\circ\text{C}$		50	μA
		$V_R = 75\text{V}$		5.0	μA
C_T	Total Capacitance	$V_R = 0\text{V}, f = 1.0\text{MHz}$		4.0	pF
t_{rr}	Reverse Recovery Time	$I_F = 10\text{mA}, V_R = 6.0\text{V}, I_{RR} = 1.0\text{mA}, R_L = 100\Omega$		4.0	ns

Typical Characteristics

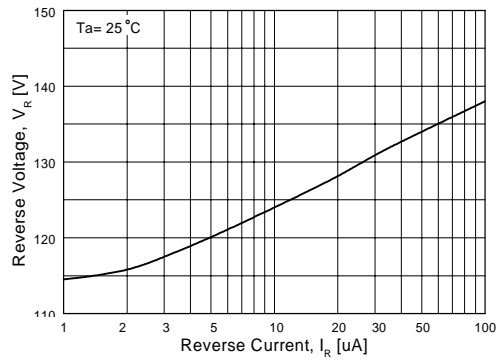


Figure 1. Reverse Voltage vs Reverse Current
BV - 1.0 to 100 μ A

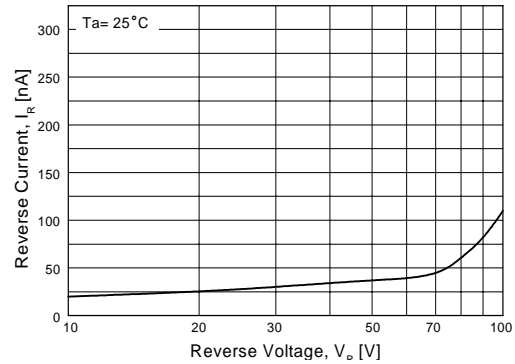


Figure 2. Reverse Current vs Reverse Voltage
IR - 10 to 100 V

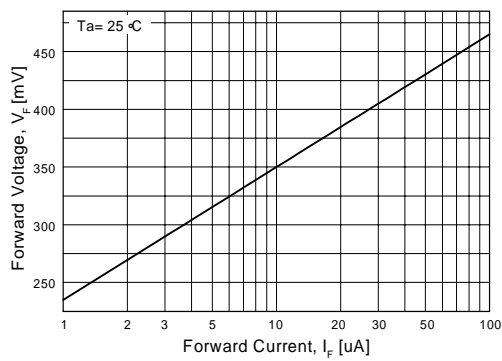


Figure 3. Forward Voltage vs Forward Current
VF - 1.0 to 100 μ A

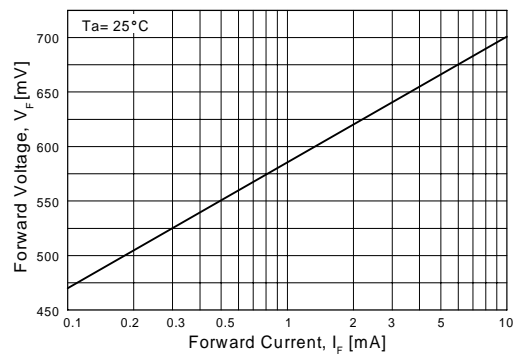


Figure 4. Forward Voltage vs Forward Current
VF - 0.1 to 10 mA

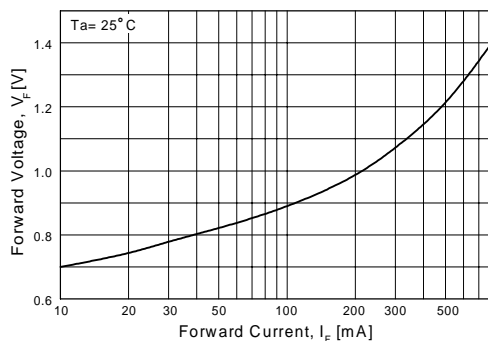


Figure 5. Forward Voltage vs Forward Current
VF - 10 - 800 mA

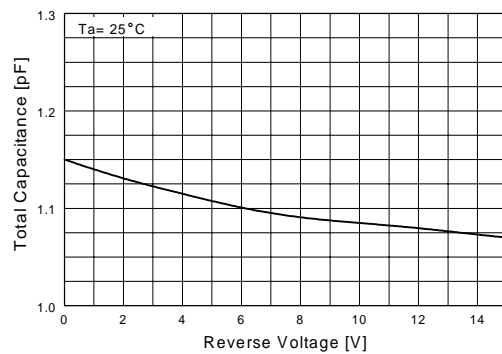


Figure 6. Total Capacitance vs Reverse Voltage

Typical Characteristics (continued)

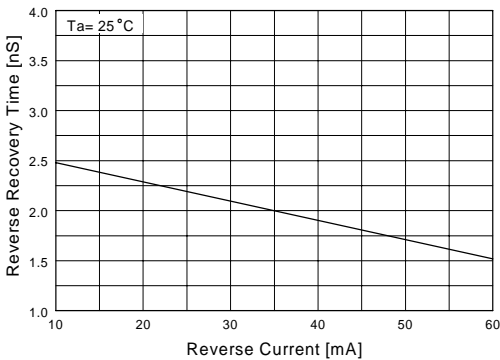


Figure 7. Reverse Recovery Time
vs Reverse Current
TRR - IR 10 mA vs 60 mA

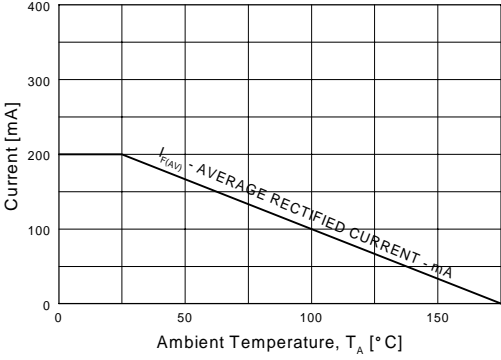


Figure 8. Average Rectified Current ($I_{F(AV)}$)
versus Ambient Temperature (T_A)

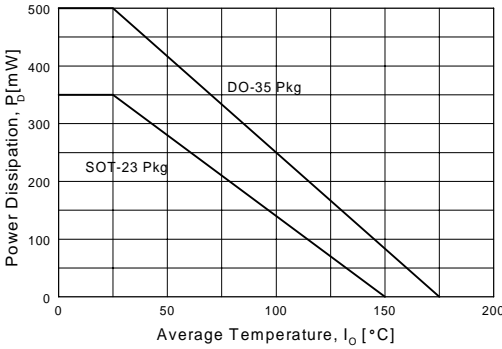


Figure 9. Power Derating Curve

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Bottomless™	FPST™	MICROCOUPLER™	PowerTrench®	SuperSOT™-6
CoolFET™	FRFET™	MicroFET™	QFET®	SuperSOT™-8
CROSSVOLT™	GlobalOptoisolator™	MicroPak™	QST™	SyncFET™
DOME™	GTO™	MICROWIRE™	QT Optoelectronics™	TinyLogic®
EcoSPARK™	HiSeC™	MSX™	Quiet Series™	TINYOPTO™
E ² CMOS™	I ² C™	MSXPro™	RapidConfigure™	TruTranslation™
EnSigna™	<i>i-Lo</i> ™	OCX™	RapidConnect™	UHC™
FACT™	ImpliedDisconnect™	OCXPro™	μSerDes™	UltraFET®
FACT Quiet Series™		OPTOLOGIC®	SILENT SWITCHER®	VCX™
Across the board. Around the world.™		OPTOPLANAR™	SMART START™	
The Power Franchise®		PACMAN™	SPM™	
Programmable Active Droop™		POP™	Stealth™	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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